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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/525,909	02/25/2005	Hidekuni Aizawa	09792909-6097	1000
26263	7590	02/09/2006	EXAMINER	
SONNENSCHN NATH & ROSENTHAL LLP P.O. BOX 061080 WACKER DRIVE STATION, SEARS TOWER CHICAGO, IL 60606-1080			NGUYEN, DILINH P	
			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 02/09/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No. 10/525,909	Applicant(s) AIZAWA ET AL.	
	Examiner DiLinh Nguyen	Art Unit 2814	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 25 February 2005.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-4 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-4 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date <u>2/25/05</u> . | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Drawings

Figures 5A-8C should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). Corrected drawings in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. The replacement sheet(s) should be labeled "Replacement Sheet" in the page header (as per 37 CFR 1.84(c)) so as not to obstruct any portion of the drawing figures. If the changes are not accepted by the examiner, the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

2. Claims 1-4 are rejected under 35 U.S.C. 102(e) as being anticipated by Applicant Admitted Prior Art (figs. 8A-8C).

Applicant Admitted Prior Art disclose a semiconductor apparatus comprising:

a housing 51 in which device mounting portions are respectively formed on both one surface side and the other surface side thereof;

a first device 57 mounted in the device mounting portion on one surface side of this housing;

a second device 59 mounted in the device mounting portion on the other surface side of the housing; and

a plurality of leads 52-56 having pad portions for wire bonding, supported by the housing while exposing those pad portions to the device mounting portions, and connected through wires 58 to the first device 57 or second device 59 in the device mounting portions, wherein

said pad portions 55B of at least one lead 55 among the plurality of leads are exposed to the device mounting portions in the position relation alternate with each other on the one surface side and the other surface side of the housing 51, and

this exposed portion serves as the connection portion of the wire bonding 58 (fig. 8B).

- Regarding claim 2, AAPA discloses that the pad portion of at least one lead 52 is formed larger than the pad portion of the other lead (figs. 8A and 8C).

- Regarding claim 3, AAPA discloses a semiconductor apparatus characterized by comprising:

a housing 51 in which device mounting portions are respectively formed on both one surface side and the other surface side;

a first device 57 mounted in the device mounting portion on said one surface side of this housing;

a second device 59 mounted in the device mounting portion on said the other surface side of the housing; and

a plurality of leads 52-56 having pad portions for wire bonding, being supported by the housing 51 while exposing those pad portions to the device mounting portions, and being connected through wires 58 to the first device 57 or second device 59 in the device mounting portions,

wherein the pad portions 55B of at least one lead 55 among the plurality of leads are exposed to the device mounting portions in the position relation alternate with each other, on the one surface side and the other surface side of the housing 51, and

this exposed portion serves as the connection portion of the wire bonding 58 (fig. 8B).

- Regarding claim 4, AAPA discloses a semiconductor apparatus characterized by comprising:

a housing 51 in which device mounting portions are respectively formed on both one surface side and the other surface side thereof;

a first device 57 mounted in the device mounting portion on said one surface side of this housing;

a second device 59 mounted in the device mounting portion on said the other surface side of the housing; and

a plurality of leads 52-56 having pad portions for wire bonding, supported by the housing 51 while exposing those pad portions to the device mounting portions, and

connected through wires 58 to the first device 57 or second device 59 in the device mounting portions,

wherein the pad portions 55B of at least one lead 55 among the plurality of leads are exposed to the device mounting portions in the position relation alternate with each other, on the one surface side and the other surface side of the housing, and

this exposed portion serves as the connection portion of the wire bonding 58 (fig. 8B).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (571) 272-1712. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

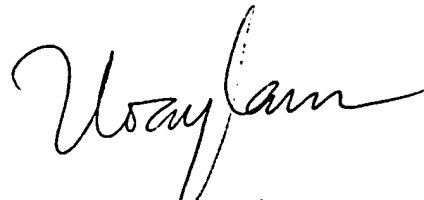
If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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HOAI PHAM
PRIMARY EXAMINER